惠州市宏旺导热制品有限公司
HONEYWON THERMALLY CONDUCTIVE PRODUCTS CO.,LTD
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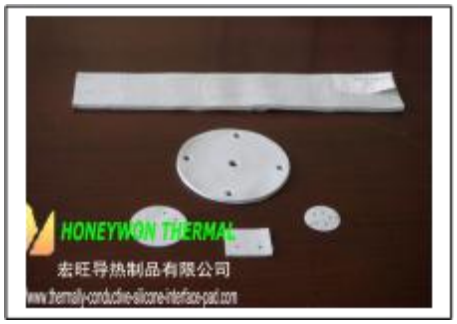
Technical Data:

Thermally Conductive Silicone Interface Pad: HWP-180



Product Features:

-Good thermal conductivity
-High conformability and cost effective
-Shock absorbing and naturally tacky
-Electrically insulating
-it is easy to fill in air gaps between PC board and heat sinks or a metal chassis

Product Applications:

- Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.
- Led Lighting, LCD TV, Telecom device, wireless Hub,NB, PC, power supply etc
- Cooling Module, Thermal module, in all applications where a metal housing is used as heatsink.

Product description:

Typical Properties of HWP-180 Pad

Properties	Units	HWP180	Test Method
Construction & Composition	---	Silicone & Ceramic filled	---
Color	---	Gray	Visual
Thickness Range	mm	0.5~12.0	---
Hardness	Shore C	18 or 35	ASTM D2240
Density	g/cc	2	ASTM D792
Tensile Strength	KN/m	1.3	ASTM D412
Elongation	%	1.35	ASTM D412
Continuous Use Temp	℃	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥4.0	ASTM D149
Volume Impedance	ohm-cm	$1.7*10^{16}$	ASTM D257
Dielectric Constant	1MHz	4.51	ASTM D150
Weight Daminify	---	≤1％	@150℃ 240H
Flame Rating	---	V0	UL 94
Thermal Conductivity	W/m.k	1.8	ASTM D5470
UL, RoHS, REACH	---	Compliance	---